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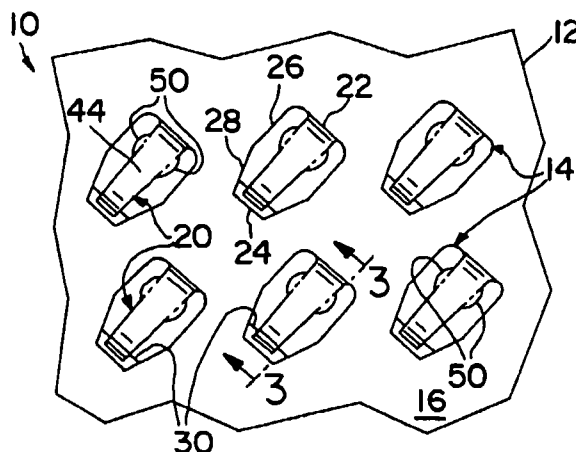
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(54) Title: **INTERPOSER ASSEMBLY AND METHOD**(57) Abstract: An interposer assembly (10) includes
a dielectric plate (12) having a plurality of contact
passages (14) extending through the plate with a contact
(20) in each passage. Each contact includes a pair of
laterally spaced contact points (50) at the top and bottom
of the plate. Sandwinching of the interposer assembly
between two substrates (86) brings the contact points
on each spring arm (42) into engagement with a pad
(84), elastically bends the contacts and forms redundant
high pressure wiped electrical connections between the
contact points and pads.

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